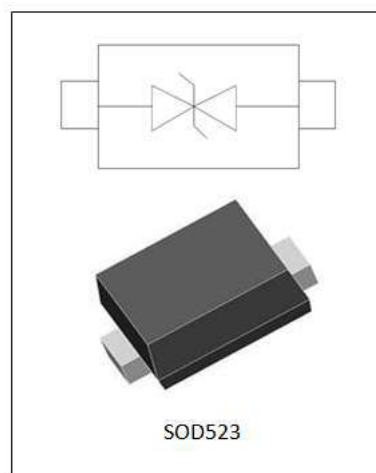


Surface Mount Transient Voltage Suppressor

TVS Diode

Features

- ◆ 150 Watts peak pulse power ($t_p = 8/20\mu s$)
- ◆ Transient protection for high speed data lines to IEC 61000-4-2 (ESD) $\pm 15kV$ (air), $\pm 8kV$ (contact) IEC 61000-4-4 (EFT) 40A(5/50ns)
- ◆ Protects One Power or I/O Port
- ◆ Low leakage current
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon avalanche technology



Applications

- ◆ Cell Phone Handsets and Accessories
- ◆ Microprocessor based equipment
- ◆ Portable Instrumentation
- ◆ Personal Digital Assistant(PDA)

Maximum Rating @ $T_a = 25^\circ C$ unless otherwise specified

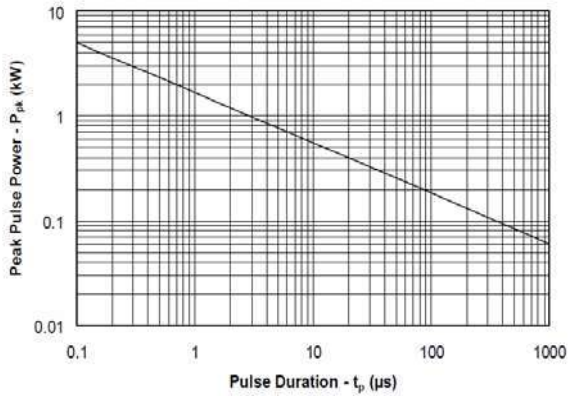
| Symbol | Parameter | Ratings | Units |
|-----------|--|-------------|------------|
| P_{PK} | Peak Pulse Power ($t_p = 8/20\mu s$) | 150 | Watts |
| T_L | Lead Soldering Temperature | 260(10sec.) | $^\circ C$ |
| T_J | Operating Temperature | -55 to +125 | $^\circ C$ |
| T_{STG} | Storage Temperature | -55 to +150 | $^\circ C$ |

Electric Characteristics @ $T_a = 25^\circ C$ unless otherwise

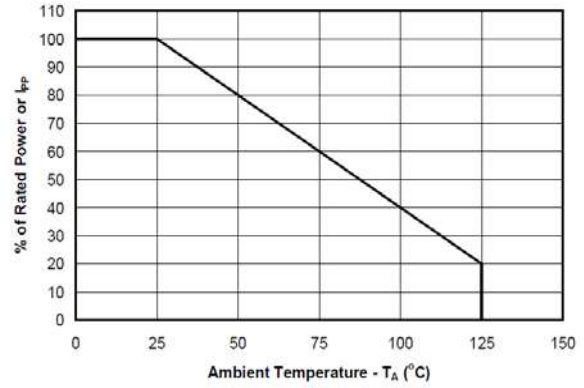
| Parameter | Marking | VRWM @IR | | VBR@ImA | VC@1A | VC@IPP | | CJ |
|-------------|---------|----------|---------|---------|-------|--------|---|-----|
| | | V | μA | V | V | V | A | pF |
| | | | MAX | MIN | MAX | MAX | | MAX |
| KWESD5Z5.0C | | 5 | 1 | 6 | 9.8 | 15 | 8 | 30 |

Typical Characteristics@ $T_a=25^\circ\text{C}$ unless otherwise specified

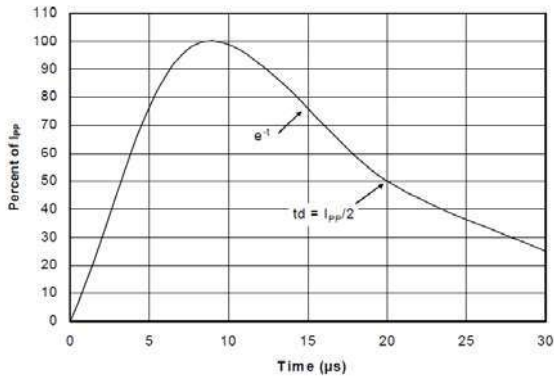
Non-Repetitive Peak Pulse Power vs. Pulse Time



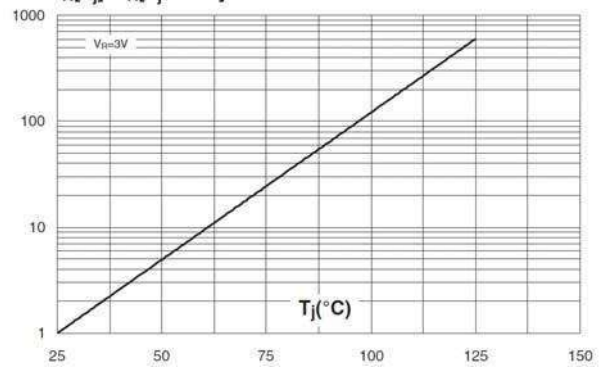
Power Derating Curve



Pulse Waveform

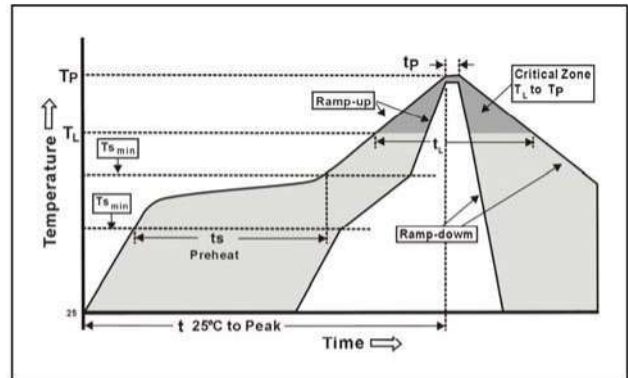


$I_R[T_J] / I_R[T_J=25^\circ\text{C}]$



Soldering Parameters

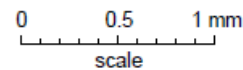
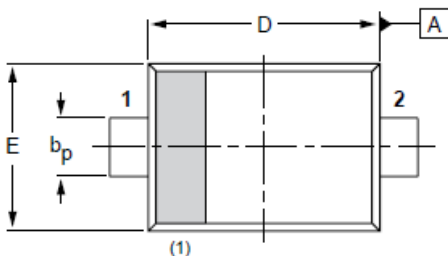
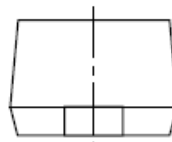
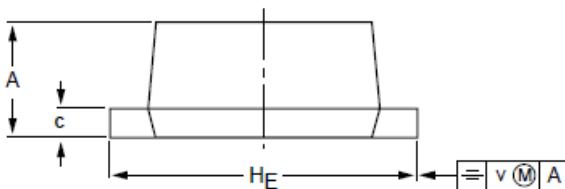
| | | |
|--|------------------------------------|-------------------------|
| Reflow Condition | | Fb – Free assembly |
| Pre Heat | - Temperature Min ($T_{s(Min)}$) | 150°C |
| | - Temperature Max ($T_{s(Max)}$) | 200°C |
| | - Time (Min to max) (t_s) | 60 – 180 secs |
| Average ramp up rate (Liquidus) Temp (T_L) to peak | | 3°C/second Max |
| $T_{s(Max)}$ to T_L - Ramp-up Rate | | 3°C/second Max |
| Reflow | - Temperature (T_L) (Liquidus) | 217°C |
| | - Temperature (t_L) | 60 – 150 seconds |
| Peak Temperature (T_p) | | 250 ^{+0/-5} °C |
| Time within 5°C of actual peak Temperature (t_p) | | 20 – 40 seconds |
| Ramp-down Rate | | 6°C/second Max |
| Time 25°C to peak Temperature (T_p) | | 8 minutes Max. |
| Do not exceed | | 260°C |



Package Outline

Plastic surface mounted package

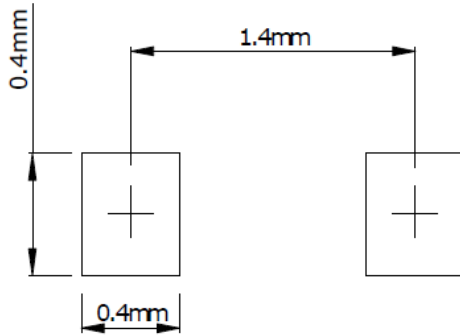
SOD523



DIMENSIONS (mm are the original dimensions)

| UNIT | A | b _p | c | D | E | H _E | v |
|------|--------------|----------------|--------------|--------------|--------------|----------------|-----|
| mm | 0.65 0.58 | 0.34 0.26 | 0.17 0.11 | 1.25 1.15 | 0.85 0.75 | 1.65 1.55 | 0.1 |

Soldering Footprint



Package And Marking Information

| Device | Package | Shipping | Reel Size |
|-------------|---------|-----------|-----------|
| KWESD5Z5.0C | SOD523 | 3000/Reel | 7 inch |